

**IN THE SPECIFICATION**

Please amend the Specification as follows:

Please delete the Title in its entirety and insert therefor --- A CLOSED AIR GAP  
INTERCONNECT STRUCTURE ---

The paragraph on page 27, lines 19-23 should be changes as follows:

--- Next, following an optional wet or dry clean to remove any residues caused by the  
etch process, the line and via openings are filled with a thin conformal conductive liner  
[[2130]]by means of either a physical vapor deposition (PVD), atomic layer deposition (ALD) or  
a chemical vapor deposition (CVD) process. ---